WHAT IS CLAIMED IS:

1. A holding jig comprising:

an elastic material wherein at least the surface thereof is adhesive and conductive, and wherein an electronic part or component constituting the electronic part is holdable by the adhesive strength of the surface of the elastic material.

2. The holding jig according to claim 1, wherein the elastic material is made to be conductive by adding conductive material to the elastic material.

3. The holding jig according to claim 1, wherein the elastic material is made to be conductive by installing a wiring using conductive material on the surface of the elastic material.

4. The holding jig according to claim 1, wherein the elastic material is made to be conductive by installing a wiring using conductive material inside the elastic material, the wiring being exposed on the surface of the elastic material.

5. A method of holding an electronic part or a component constituting the electronic part, comprising:

holding said electronic part or a component constituting the electronic part on a surface of an elastic material, in which at least the surface of a said elastic material is adhesive and conductive, by the adhesive strength of said surface.

6. A method of manufacturing electronic parts, comprising:

holding a substrate on a surface of an elastic material, in which at least the surface of said elastic material is adhesive and conductive, by the adhesive strength of said surface; and

mounting and electrically connecting an element on said substrate while said substrate is held on the surface of said elastic material.

7. A method of manufacturing electronic parts, comprising:

holding a substrate on a surface of an elastic material, in which at least the surface of said elastic material is adhesive, by the adhesive strength of said surface; and

mounting and electrically connecting an element on said substrate while the substrate is held on the surface of the elastic material.

8. The method of manufacturing electronic parts according to claim 7, further including, applying ultrasonic waves to the bonding portion at which the electric connection is performed.

9. The method of manufacturing electronic parts according to claim 7, wherein the hardness of the elastic material is a rubber hardness degree of at least A30.

10. The method of manufacturing electronic parts according to claim 7, wherein the holding jig comprises heat-resistant material having a heat-resistance temperature of about 250°C.

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11. The method of manufacturing electronic parts according to claim 7, wherein the holding jig includes a laminate structure of a hard plate and the elastic material.

12. The method of manufacturing electronic parts according to claim 7, wherein the elastic material comprises silicone resin.

13. The method of manufacturing electronic parts according to claim 7, wherein the mounting process includes a wire bonding process.

14. The method of manufacturing electronic parts according to claim 7, wherein the mounting process includes a bump bonding process.

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